

#### **Product Summary**

- V<sub>R</sub> = 40V
- I<sub>F</sub> = 0.52A
- I<sub>R</sub> = 10μA

### **Description and Applications**

This compact SOD323 packaged Schottky diode offers users an excellent performance combination comprising high current operation, extremely low leakage and low forward voltage ensuring suitability for applications requiring efficient operation at higher temperatures (above 85°C) see Operational efficiency chart on page 4.

- DC DC Converters
- Mobile Telecomms
- Charging circuits
- Motor control

#### **40V SURFACE MOUNT SCHOTTKY BARRIER DIODE**

#### **Features and Benefits**

- Low Equivalent On Resistance
- Extremely low leakage (10μA @30V)
- High current capability (I<sub>F</sub> = 0.52A)
- Low V<sub>F</sub>, fast switching Schottky
- ZLLS400 complements low temperature equivalent ZHCS400
- Package thermally rated to 150°C
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOD323
- Case Material: UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.004 grams (approximate)

SOD323



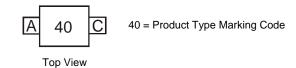
Top View

### Ordering Information (Note 1)

Device	Packaging	Shipping
ZLLS400TA	SOD323	3,000/Tape & Reel
ZLLS400TC	SOD323	10,000/Tape & Reel

Notes: 1. For Packaging Details, go to our website at http://www.diodes.com.

#### Marking Information



ZLLS400 Document number: DS33226 Rev. 7 - 2



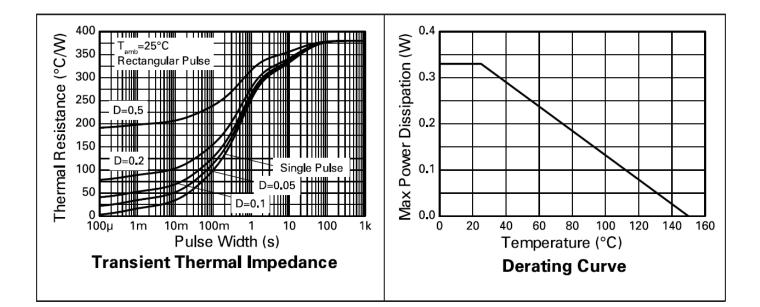
#### Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Units
Continuous Reverse Voltage		V <sub>R</sub>	40	V
Continuous Forward Current		I <sub>F</sub>	0.52	А
Peak Repetitive Forward Current Rectangular Pulse Duty Cycle		Ігрк	0.85	А
Non Repetitive Forward Current	t ≤ 100μs	1	12	А
	t ≤ 10ms	IFSM	2.5	А

#### **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Power Dissipation, $T_A = 25^{\circ}C$ Single Die Continuous Single Die Measured at t < 5 secs		PD	330 390	mW
Thermal Resistance, Junction to Ambiet	(Note 2) (Note 3)	R <sub>θJA</sub>	379 317	°C/W
Junction Temperature		TJ	150	°C
Storage Temperature Range		T <sub>STG</sub>	-55 to +150	°C

Notes: 2. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions. 3. For a device surface mounted on FR4 PCB measured at t<5 secs.



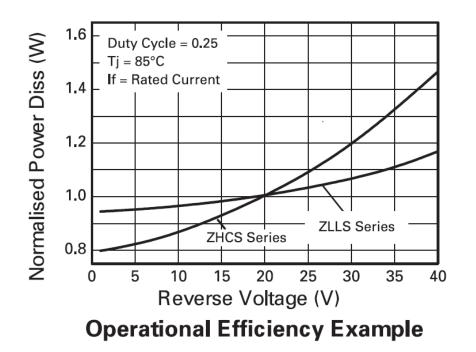


#### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage	V <sub>(BR)R</sub>	40	60	-	V	I <sub>R</sub> = 200μA
Forward Voltage (Note 4)		-	305	360	mV	$I_F = 50 \text{mA}$
		-	335	390		I <sub>F</sub> = 100mA
		-	395	450		I <sub>F</sub> = 250mA
	V	-	445	500		I <sub>F</sub> = 400mA
	V <sub>F</sub>	-	550	630		I <sub>F</sub> = 750mA
		-	620	710		I <sub>F</sub> = 1A
		-	710	800		I <sub>F</sub> = 1.5A
		-	405	-		I <sub>F</sub> = 400mA, T <sub>A</sub> = 100°C
Reverse Current		-	6	10	μΑ	V <sub>R</sub> = 30V
	I <sub>R</sub>	-	370	-		V <sub>R</sub> = 30V, T <sub>A</sub> = 85°C
Diode Capacitance	CD	-	15	-	pF	f = 1MHz, V <sub>R</sub> = 30V
Reverse Recovery Time	trr	-	3	-	ns	Switched from $I_F = 500 \text{mA}$ to
Reverse Recovery Charge	Qrr	-	210	-	рС	$V_R = 5.5V$ Measured @ $I_R = 50mA$ di /d t = 500mA / ns $R_{source} = 6\Omega$ ; $R_{load} = 10\Omega$

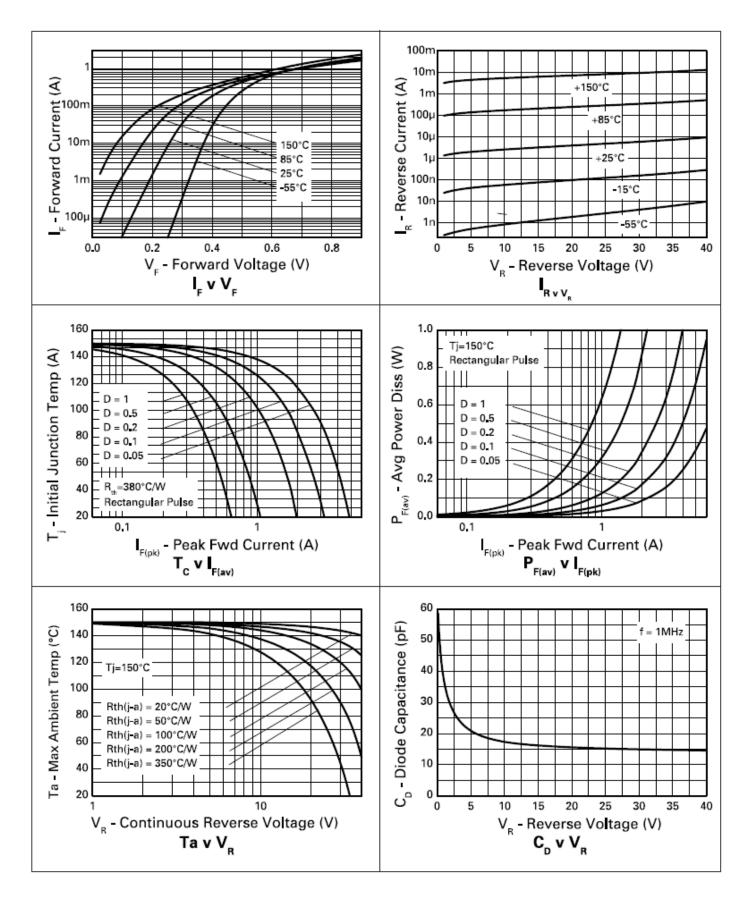
Notes: 4. Measured under pulsed conditions. Pulse width =  $300\mu$ S. Duty cycle – 2%.

### **Operational efficiency chart**



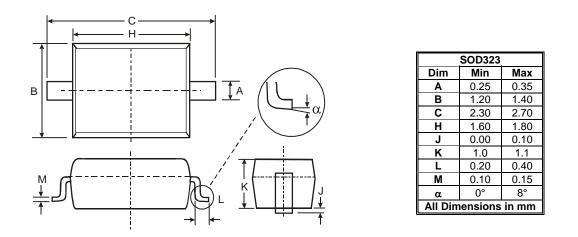
The operational efficiency chart indicates the beneficial use of the ZLLS series diodes in applications requiring higher voltage, higher temperature operation. Circuits requiring low voltage low temperature operation will benefit from using Zetex low V<sub>F</sub> ZHCS series diodes.



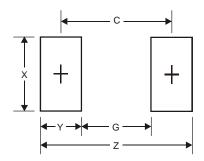




# Package Outline Dimensions



## Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.75
G	1.05
Х	0.65
Y	1.35
С	2.40



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